

ABSTRACT

A packaging process for improving effective chip-bonding area is disclosed in the present invention. An A-stage liquid paste is formed on a substrate and partially cured to become a B-stage film layer. The B-stage film layer is maintained without fully cured passing through a chip-attaching step and an electrically connecting step. During the molding step, the packing pressure for the molding compound (1000psi~1500psi) is larger than the chip attaching pressure for enabling the B-stage film layer to be closely compressed in order to improve effective chip-bonding area. The B-stage film layer and the molding compound are cured simultaneous in the molding step.